

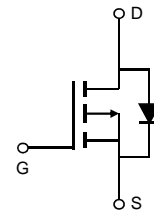
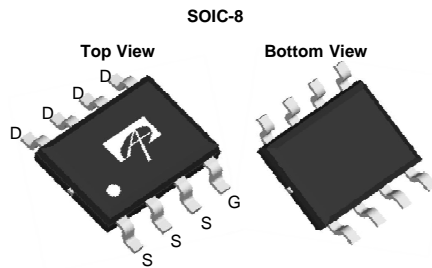
### General Description

The AO4453 combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for load switch and battery protection applications.

### Product Summary

$V_{DS}$	-12V
$I_D$ (at $V_{GS}=-4.5V$ )	-9A
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$ )	< 19m $\Omega$
$R_{DS(ON)}$ (at $V_{GS}=-3.3V$ )	< 22m $\Omega$
$R_{DS(ON)}$ (at $V_{GS}=-2.5V$ )	< 26m $\Omega$
$R_{DS(ON)}$ (at $V_{GS}=-1.8V$ )	< 36m $\Omega$
$R_{DS(ON)}$ (at $V_{GS}=-1.5V$ )	< 50m $\Omega$

100% UIS Tested  
 100%  $R_g$  Tested



### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	-12	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current	$I_D$	$T_A=25^\circ C$	-9
		$T_A=70^\circ C$	-7
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	-55	A
Avalanche Current <sup>C</sup>	$I_{AS}$	20	A
Avalanche energy $L=0.1mH$ <sup>C</sup>	$E_{AS}$	20	mJ
Power Dissipation <sup>B</sup>	$P_D$	$T_A=25^\circ C$	2.5
		$T_A=70^\circ C$	1.6
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	42	50	$^\circ C/W$
Maximum Junction-to-Ambient <sup>A,D</sup>		Steady-State	70	85
Maximum Junction-to-Lead	$R_{\theta JL}$	20	30	$^\circ C/W$

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V	-12			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-12V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			-1 -5	μA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±8V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.3	-0.6	-0.9	V
I <sub>D(ON)</sub>	On state drain current	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-5V	-55			A
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-9A T <sub>J</sub> =125°C		15	19	mΩ
				19.5	25	
		V <sub>GS</sub> =-3.3V, I <sub>D</sub> =-7A		17	22	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-6A		20	26	mΩ
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-4A		27	36	mΩ
		V <sub>GS</sub> =-1.5V, I <sub>D</sub> =-1A		33	50	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-9A		-33		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V		-0.6	-1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				-3.5	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-6V, f=1MHz		1370		pF
C <sub>oss</sub>	Output Capacitance			350		pF
C <sub>riss</sub>	Reverse Transfer Capacitance			258		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		10	20	Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g(4.5V)</sub>	Total Gate Charge	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-6V, I <sub>D</sub> =-9A		12.7	18	nC
Q <sub>gs</sub>	Gate Source Charge			1.7		nC
Q <sub>gd</sub>	Gate Drain Charge			3.4		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-6V, R <sub>L</sub> =0.67Ω, R <sub>GEN</sub> =3Ω		11		ns
t <sub>r</sub>	Turn-On Rise Time			25		ns
t <sub>D(off)</sub>	Turn-Off DelayTime			70		ns
t <sub>f</sub>	Turn-Off Fall Time			41.5		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time		I <sub>F</sub> =-9A, di/dt=100A/μs		20.7	
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =-9A, di/dt=100A/μs		5.2		nC

A. The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150° C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150° C. Ratings are based on low frequency and duty cycles to keep initial T<sub>J</sub>=25° C.

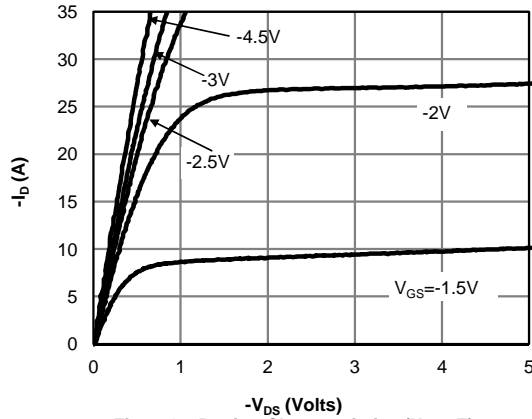
D. The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

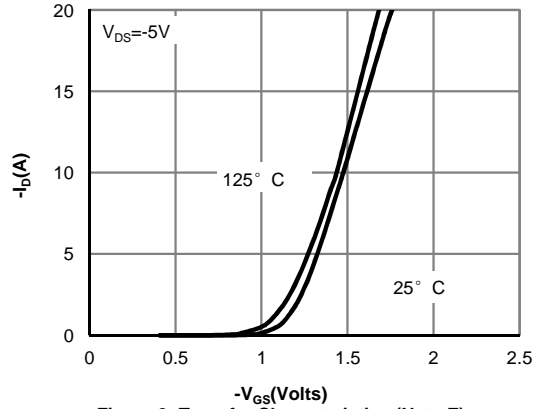
F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T<sub>J(MAX)</sub>=150° C. The SOA curve provides a single pulse rating.

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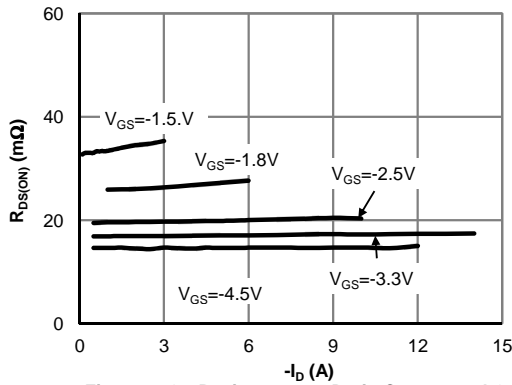
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**



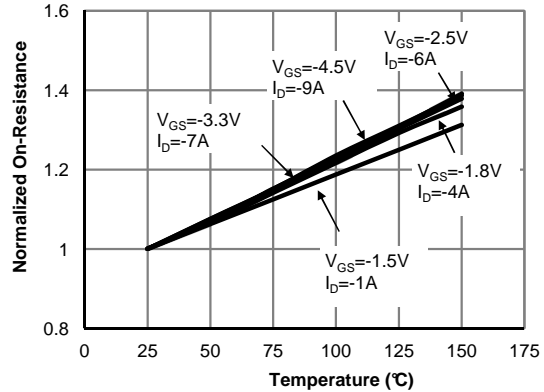
**Fig 1: On-Region Characteristics (Note E)**



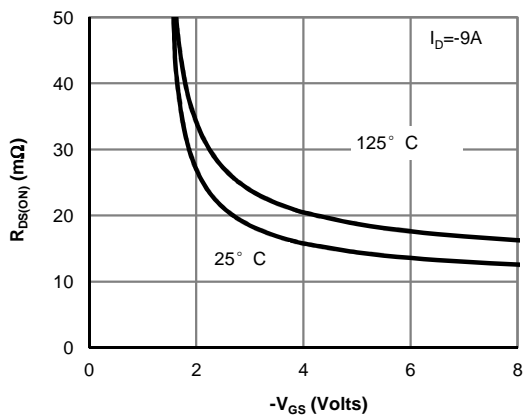
**Figure 2: Transfer Characteristics (Note E)**



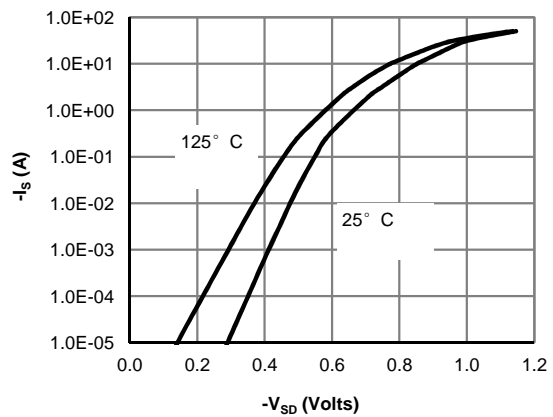
**Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)**



**Figure 4: On-Resistance vs. Junction Temperature (Note E)**

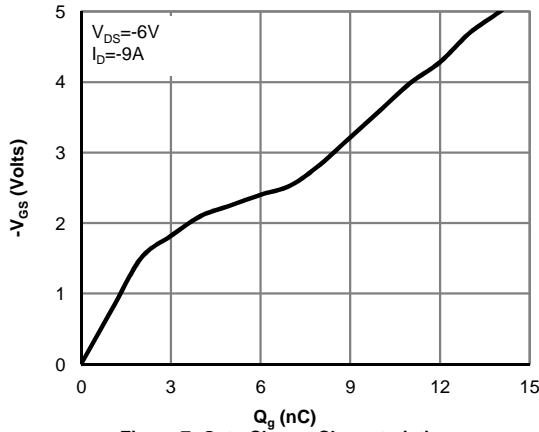


**Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)**

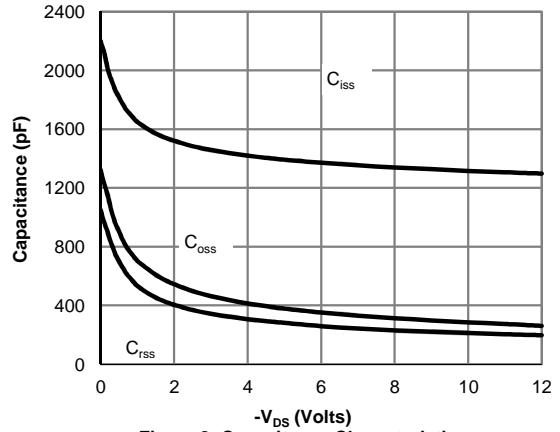


**Figure 6: Body-Diode Characteristics (Note E)**

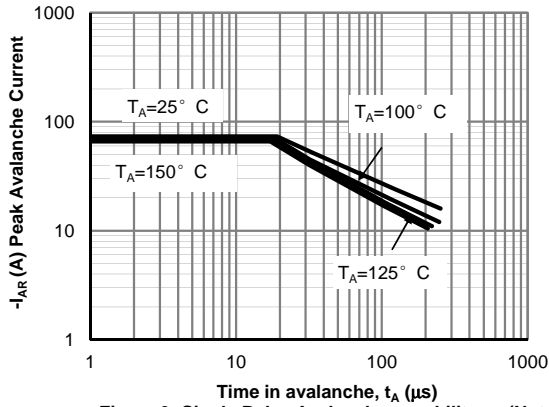
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**



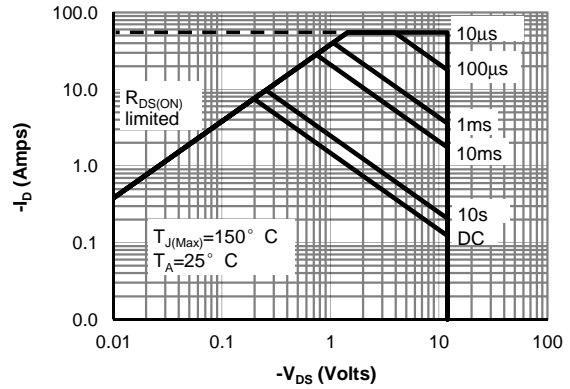
**Figure 7: Gate-Charge Characteristics**



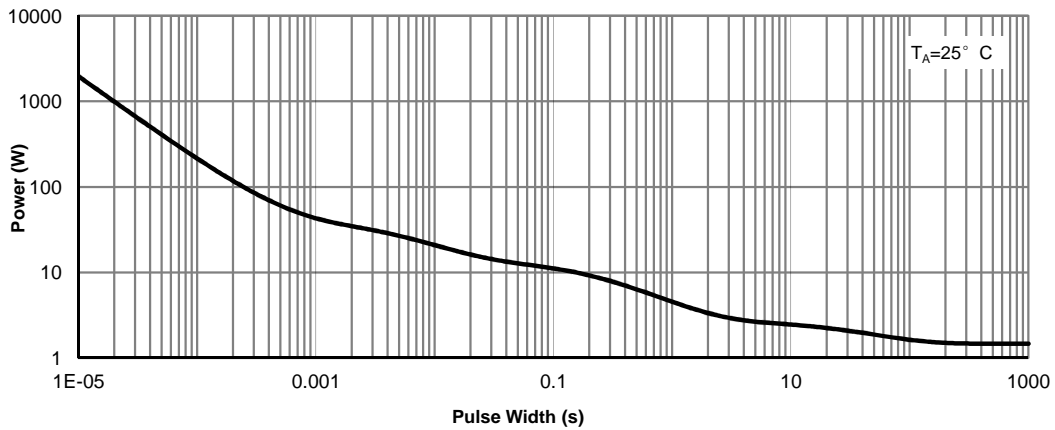
**Figure 8: Capacitance Characteristics**



**Figure 9: Single Pulse Avalanche capability (Note C)**

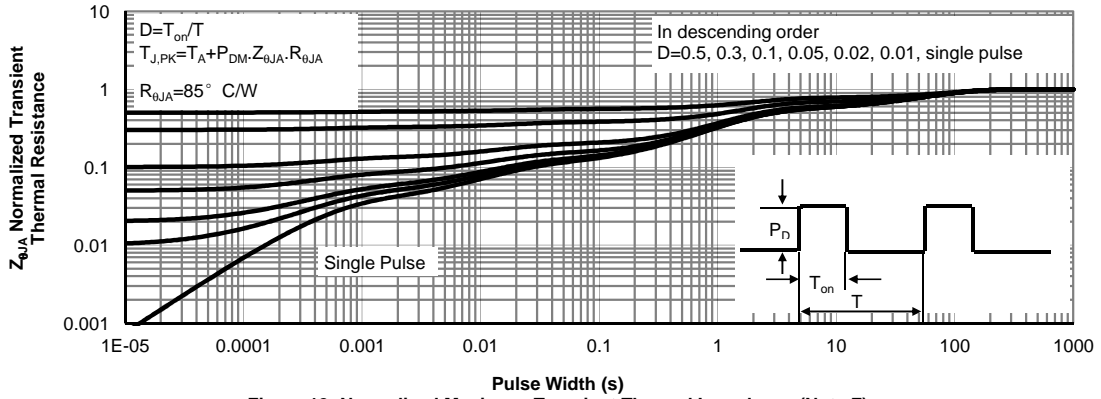


**Figure 10: Maximum Forward Biased Safe Operating Area (Note F)**



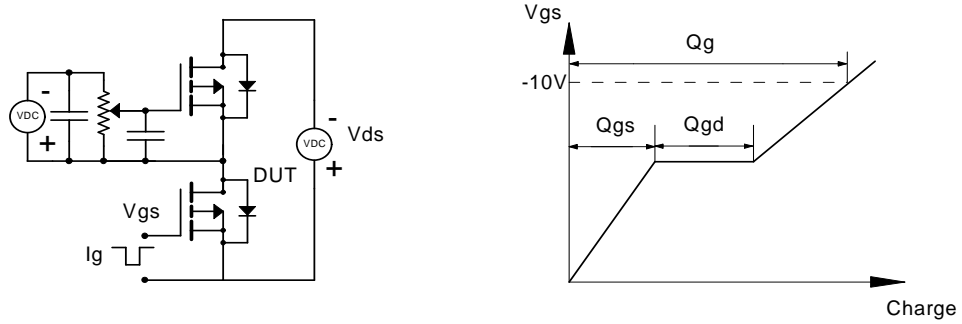
**Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)**

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

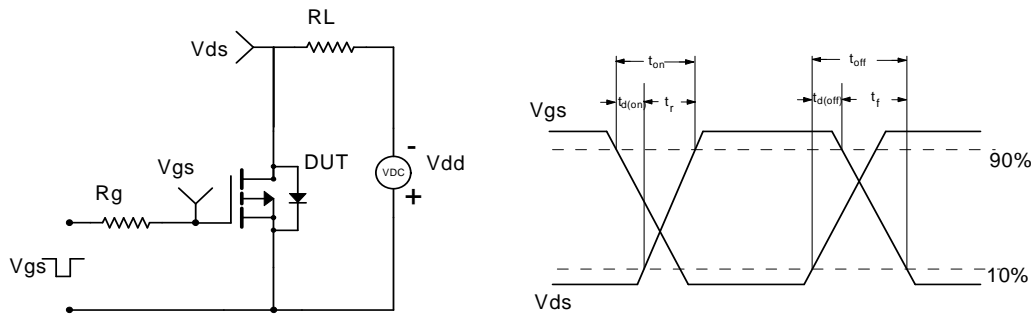


**Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)**

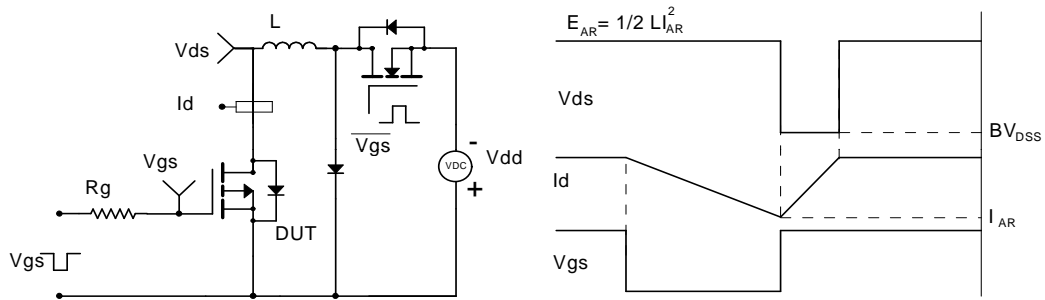
**Gate Charge Test Circuit & Waveform**



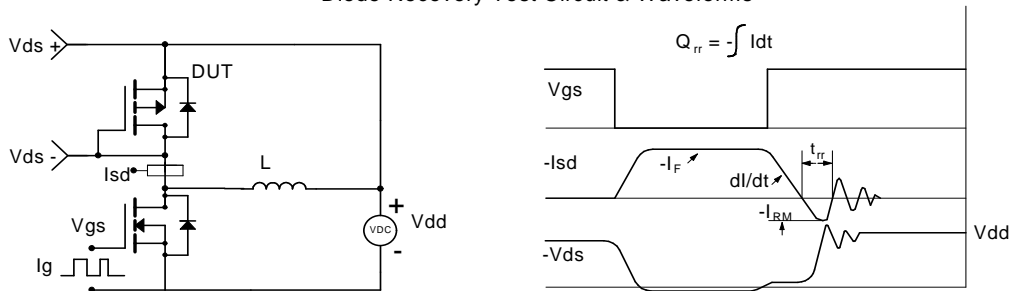
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**



**Diode Recovery Test Circuit & Waveforms**





Document No.	PD-01962
Version	A
Title	AO4453 Marking Description

SO-8 PACKAGE MARKING DESCRIPTION



Green product

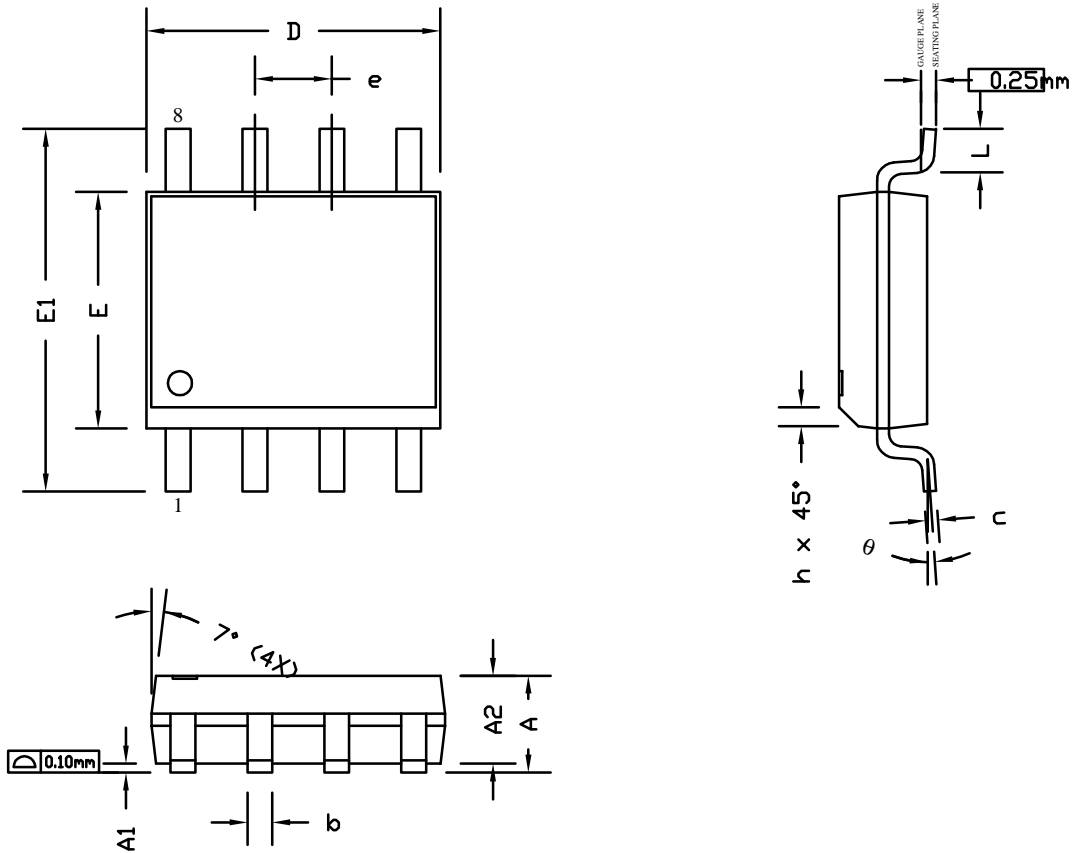
NOTE:

LOGO - AOS Logo  
AO4453 - Part number code  
F - Fab code  
A - Assembly location code  
Y - Year code  
W - Week code  
L&T - Assembly lot code

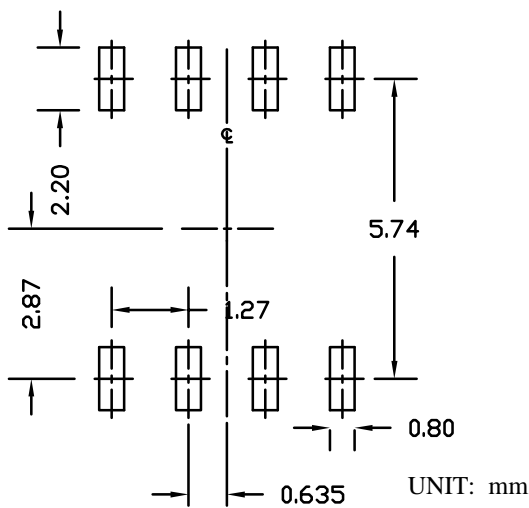
PART NO.	DESCRIPTION	CODE
AO4453	Green product	4453
AO4453L	Green product	4453



S08 PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.35	1.65	1.75	0.053	0.065	0.069
A1	0.10	0.15	0.25	0.004	0.006	0.010
A2	1.25	1.50	1.65	0.049	0.059	0.065
b	0.31	0.41	0.51	0.012	0.016	0.020
c	0.17	0.20	0.25	0.007	0.008	0.010
D	4.80	4.90	5.00	0.189	0.193	0.197
E	3.80	3.90	4.00	0.150	0.154	0.157
e	1.27 BSC			0.050 BSC		
E1	5.80	6.00	6.20	0.228	0.236	0.244
h	0.25	0.30	0.50	0.010	0.012	0.020
L	0.40	0.69	1.27	0.016	0.027	0.050
theta	0°	4°	8°	0°	4°	8°

NOTE

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS ARE INCLUSIVE OF PLATING.
3. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.  
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
4. DIMENSION L IS MEASURED IN GAUGE PLANE.
5. CONTROLLING DIMENSION IS MILLIMETER.  
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

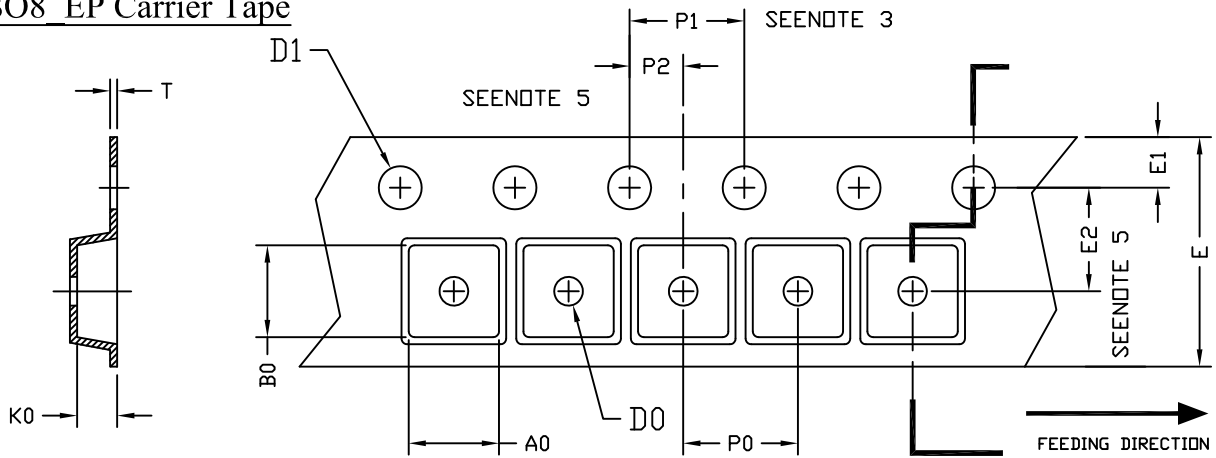




# ALPHA & OMEGA SO8/SO8\_EP Tape and Reel Data

SEMICONDUCTOR, LTD.

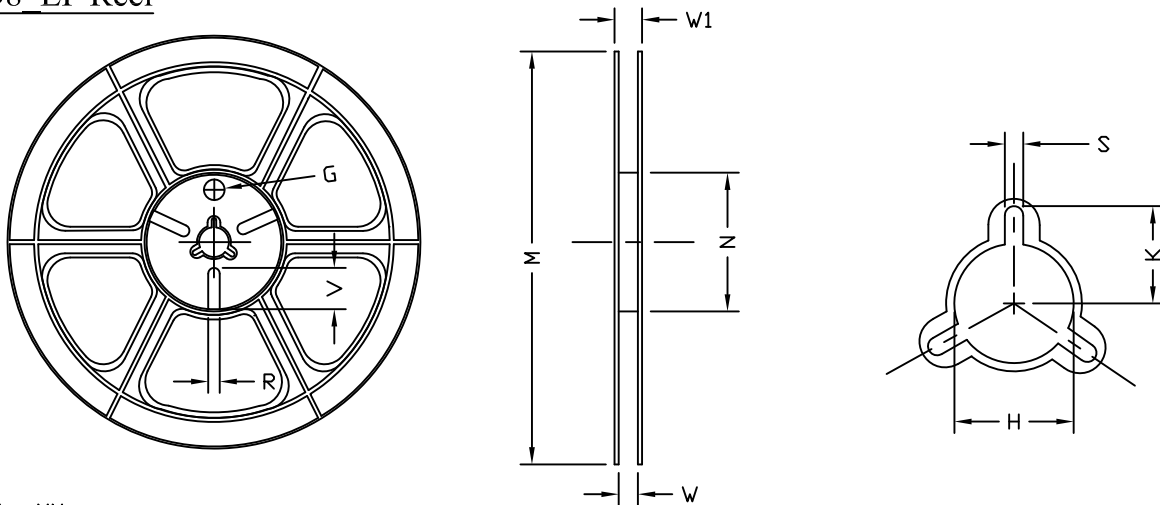
## SO8/SO8 EP Carrier Tape



UNIT: MM

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SO-8 (12 mm)	6.40 ±0.10	5.20 ±0.10	2.10 ±0.10	1.60 ±0.10	1.50 +0.10	12.00 ±0.30	1.75 ±0.10	5.50 ±0.05	8.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.25 ±0.05

## SO8/SO8 EP Reel



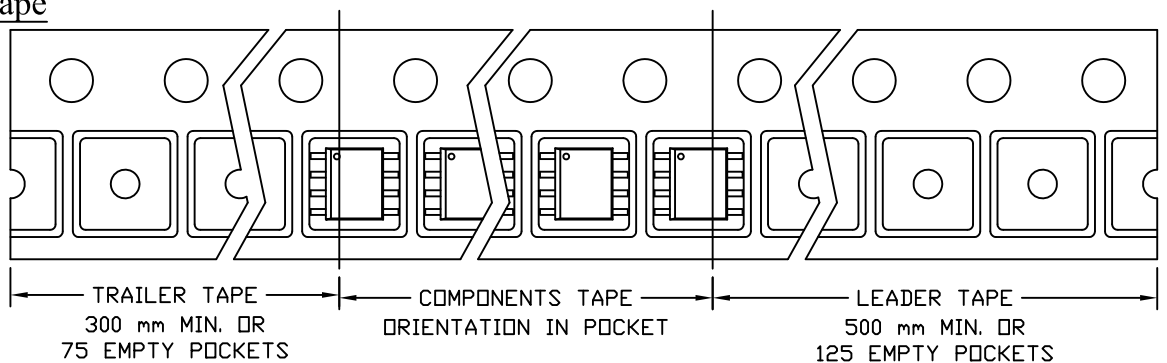
UNIT: MM

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
12 mm	∅330	∅330.00 ±0.50	∅97.00 ±0.10	13.00 ±0.30	17.40 ±1.00	∅13.00 +0.50 -0.20	10.60	2.00 ±0.50	---	---	---

## SO8/SO8 EP Tape

Leader / Trailer  
& Orientation

Unit Per Reel:  
3000pcs



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